

SANYO Semiconductors

DATA SHEET



Monolithic Linear IC 3ch Switching Regulator Control IC

Overview

The LA5679T is an 3ch switching regulator control IC.

Functions

- Operable on low voltage, min 1.8V.
- OUT1 to drive an external PNP.
- OUT2 to 3 to drive an external NPN.
- 3ch independent standby circuit incorporated.
- Reference voltage accuracy $\pm 1\%$.
- MOS transistor driving possible.

Specifications

Absolute Maximum Ratings at Ta = 25°C

Parameter	Symbol	Conditions	Ratings	Unit
Maximum supply voltage	V _{CC} max		14	V
Allowable power dissipation	Pd max	Independent IC	0.4	W
Operating temperature	Topr		-20 to +85	°C
Storage temperature	Tstg		-55 to +150	°C

Operating Conditions at $Ta = 25^{\circ}C$

Parameter	Symbol	Conditions	Ratings	Unit
Supply voltage 1	V _{CC}		1.8 to 11	V
Supply voltage 2	VBIAS		1.8 to 11	V
Output sync current	ISINK max		0 to 30	mA
Reference voltage output current	IREF		0 to 1	mA
Timing resistor	RT		3 to 30	kΩ
Timing capacity	СТ		100 to 1000	pF
Triangular wave frequency	fosc		0.1 to 1	MHz

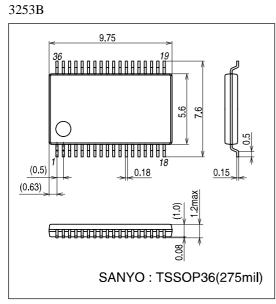
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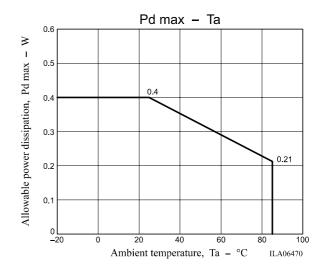
Electrical Characteristics at $Ta = 25^{\circ}C$, $V_{CC} = VSTBY1$ to 3 = 3V, SCP = 0V

Parameter		Symbol	Conditions	Ratings			Unit
				min	typ	max	0
[Error amplifier]				T	T		
IN+pin internal bias voltage	1	VB_IN+	IN2+, IN3+ pin	0.500	0.506	0.512	V
Output "Low" voltage	CH1	VLow_FB1	IN1- = 0.5V, IN1+ = 0V, IFB1 = 20μA			1	V
	CH2, CH3	VLow_FB2	IN2, 3- = 1V			0.2	V
Output "Hi" voltage	CH1	VHi_FB1	IN1- = 0.5V, IN1+ = 2V, IFB1 = -20µA	2.25			V
	CH2, CH3	VHi_FB2	IN2, 3- = 0V	0.81			V
Common-mode input	CH1	VICM_IN		0		2	V
voltage range				Ũ		2	v
[Protection circuit]							
Threshold voltage		VSCP		1.1	1.25	1.4	V
[SCP pin current]		ISCP			3.8		μA
[Still period adjusting section]]						
Input bias current		IB_DTC		-15	-3		μA
Threshold voltage 1	CH1	VTH1_DTC	FB1 = 0.5V Duty cycle = 100%	0.35	0.4	0.45	V
Threshold voltage 2	CH1	VTH2_DTC	FB1 = 0.5V Duty cycle = 0%	0.67	0.77	0.87	V
Threshold voltage 3	CH2, CH3	VTH3_DTC	FB2, 3 = 1V Duty cycle = 100%	0.80	0.88	0.96	V
Threshold voltage 4	CH2, CH3	VTH4_DTC	FB2, 3 = 1V Duty cycle = 0%	0.40	0.45	0.50	V
[Output block 1 (ch1)]	•	-		I	I		
OUT pin source current		I _{OUT} 1_SOUR	FB1 = 2V, DTC1 = 0V, RSET1 = 3.3Ω, V _{OUT} 1 = 2.7V, ICAPH = 0.5mA	10			mA
OUT pin sync current		I _{OUT} 1_SINK	FB1 = 0.5V, DTC1 = 0V, RSET1 = 3.3Ω, V _{OUT} 1 = 2.3V	20	30	40	mA
ISET pin voltage		VISET	FB1 = 0.5V, DTC1 = 0V, RSET1 = 3.3Ω, V _{OUT} 1 = 2.3V	0.065	0.1	0.135	v
[Output block 2 to 3 (ch2 to c	h3)]						
OUT pin source current	10/]	I _{OUT} 23_SOUR	RSET2, 3 = 680Ω, V _{OUT} 2, 3 = 0.9V,				
		100123_0001	DTC2, 3 = 1V, FB2, 3 = 1V	20	30	40	mA
OUT pin sync current		I _{OUT} 23_SINK	RSET2, 3 = 680Ω, V _{OUT} 2, 3 = 0.3V, DTC2, 3 = 1V, FB2, 3 = 0V	30			mA
OUT pin High voltage		V _{OUT} 23_Hi	RSET2, 3 = 680Ω, I _{OUT} 2, 3= -10mA, DTC2, 3 = 1V, FB2, 3 = 1V	2			V
OUT pin low voltage		V _{OUT} 23_LOW	RSET2, 3 = 680Ω, I _{OUT} 2, 3 = 10mA, DTC2, 3=1V, FB2, 3 = 0V			0.2	V
ISET pin voltage		VISET23	RSET2, 3 = 680Ω, V _{OUT} 2, 3 = 0.9V, DTC2, 3 = 1V, FB2, 3 = 1V	0.230	0.350	0.470	V
[Triangular wave generator]			· · · · · · · · · · · · · · · · · · ·			I	
Current setting pin voltage		VT_RT	RT = 5.6kΩ	1.190	1.260	1.330	V
Output current		I _{OH} _CT	VCT = 0.5V, RT = 5.6kΩ		230		μA
Output current ratio		∆I _O _CT		0.8	1.0	1.2	
Oscillation frequency		fosc1		200	260	320	kHz
[Reference voltage block]		000	1	_20	_20		_
Reference voltage		VREF	IREF = -1mA	1.244	1.257	1.270	V
Line regulation		VLN_REF	$V_{CC} = 1.8V$ to 11V	1.2.77	1.201	1.270	mV
Load regulation		VLD_REF	IREF = -0.1mA to -1mA			10	mV
[STBY circuit]		*L0_NL1				10	
		VON_STBY		4 4 5	<u> </u>		V
ON voltage				1.15		0.0	V
OFF voltage		VOFF_STBY				0.2	
Pin input current		I _{IN} STBY	VSTBY1 to 3 = 3V			70	μA
[All circuit]							
Operating current dissipation (I _{CC} +IBIAS1 to 3)		ICC1	FB1 = 0.5V, FB2, 3 = 1V DTC1 = 0V, DTC2, 3 = 1V RSET2, 3 = 680Ω, RSET1 = 3.3Ω		12	15	mA
Standby current dissipation (I _{CC} +IBIAS1 to 3)		I _{CC} 2	VSTBY1 to 3 = 0V			1	μA

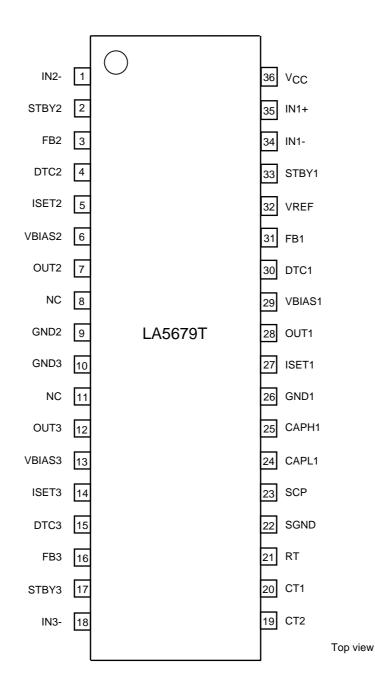
Package Dimensions

unit : mm

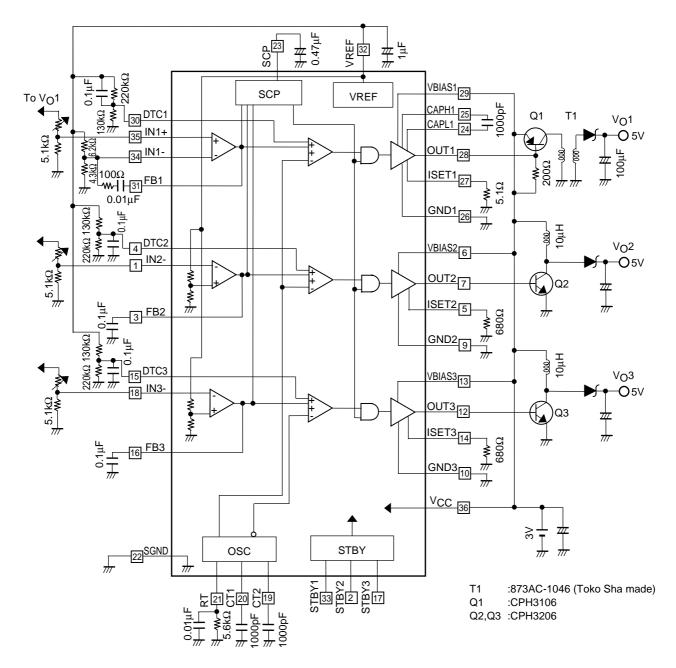




Pin Assignment



Block Diagram



Note) Soft start of Ch2 and Ch3 may not occur in certain condition. For details, refer to "Ch2 and Ch3 Soft Start" of the specification.

Output stage

(1) For Ch1

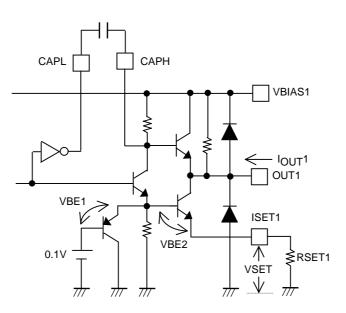
Output current I_{OUT}1 (sink) of Ch1 can be set freely by means of the resistance of ISET1 to GND and can be represented as follows:

$$I_{OUT1} = \frac{0.1 + VBE1 - VBE2}{RSET2}$$
[A]

With VBE1 = VBE2,

$$I_{OUT1} = \frac{0.1}{RSET2} \quad [A]$$

As VBE2 changes with I_{OUT} and thus VBE1 = VBE2 is not necessarily established, refer to the I_{OUT} (sink)-RSET characteristics for setting of RSET1.





(2) For Ch2 (and for Ch3)

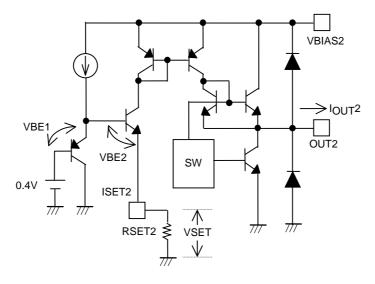
Output current I_{OUT}2 (source) can be set freely by means of the resistance of ISET2 to GND and can be represented as follows:

$$I_{OUT2} = \frac{0.4 + VBE1 - VBE2}{RSET2} \times 61.4 \text{ [A]}$$

When VBE1=VBE2,

$$I_{OUT2} = \frac{0.4}{RSET2} \times 61.4 [A]$$
 * The equation is for Ch2. The same applies to Ch3.

As VBE2 varies with ISET2, VBE1 is not always equal to VBE2. Besides, the current magnification of 61.4 varies slightly with VSET2 and I_{OUT}2. Refer to I_{OUT} (source)-RSET characteristic when setting RSET.

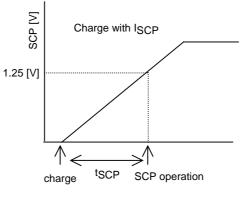


IOUT2 source current

* Figure shows a case with Ch2 as well as a case with Ch3.

SCP pin

With FB1 being LOW (FB2 and 3 HI) because of load short-circuit, SCP charge begins. If FB1 is not reset within the set time, t_{SCP}, a protective circuit is activated. (The entire OUT is turned OFF when this circuit is activated.)



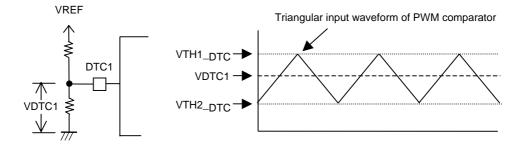
SCP charge

$$t_{SCP} = \frac{C_{SCP} \cdot V_{SCP}}{I_{SCP}} \quad [s]$$

Setting the dead time

(1) For Ch1

The dead time of Ch1 can be set with the DTC1 voltage.

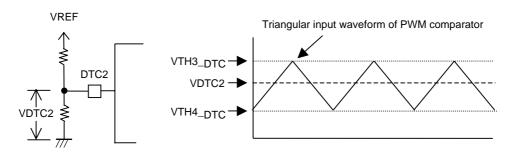


Duty D1 is represented as follows:

$$D1 = (1 - \frac{VDTC - VTH2_DTC}{VTH1_DTC - VTH2_DTC}) \times 100 [\%]$$

(2) For Ch2 (and Ch3)

The dead time of Ch2 can be set with the voltage of DTC2.



* Figure shows a case with Ch2 as well as a case with Ch3.

Duty D2 is represented as follows:

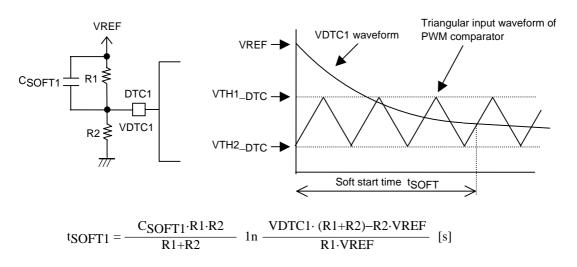
$$D2 = \frac{VDTC2 - VTH4 DTC}{VTH3 DTC - VTH4 DTC} \times 100 [\%]$$

* The equation is for Ch2. The same applies to Ch3.

Method to set the soft start time

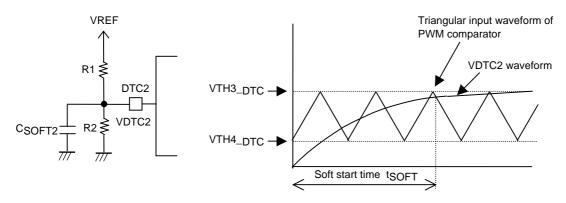
(1) For Ch1

The Ch1 soft start time is set with a capacity connected between DTC pin and VREF.



(2) For Ch2 (and Ch3)

The Ch2 soft start time is set with a capacity connected between DTC2 and 3 pins and GND.



* Figure shows a case with Ch2 as well as a case with Ch3.

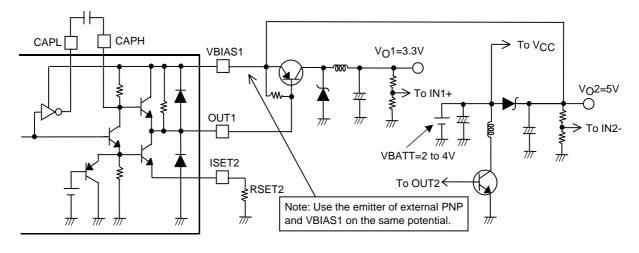
$$t_{SOFT2} = -C_{SOFT2} \cdot R2 \ln \left(1 - \frac{VDTC2}{VREF - VDTC2} \cdot \frac{R1}{R2}\right) [s]$$

* The equation is for Ch2. The same applies to Ch3.

Typical circuit using VBIAS1

As the power to the output stage is supplied with VBAIASI, the application shown in the figure can be made. The voltage of 5V stepped up with CH2 is applied to VBAIASI to obtain $V_{O1} = 3.3V$. This is stepped up/down against the change of $V_{CC} = 2$ to 4V.

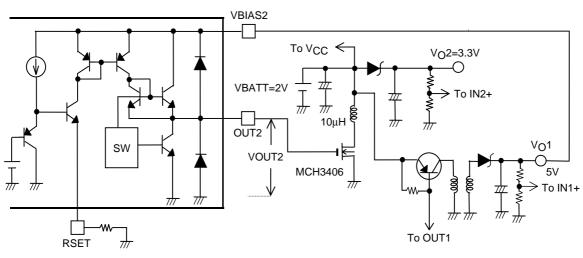
* Use the emitter of external PNP and VBAIS1 on the same potential.



Typical use of VBISA1

Typical circuit using VBIAS2 (and VBIAS3)

As the power to the output stage is supplied with VBAIAS2, the application shown in the figure can be made. The voltage of $V_{O1} = 5V$ stepped up with CH1 is applied to VBAIAS2. As the voltage of about VBIAS2-1V is generated, MOS transistor can be driven even when VBATT is low as shown in the typical circuit.



Typical VBIAS2 circuit

* Figure shows a case with VBIAS2 as well as for a case with VBIAS3.

During operation at low voltage (For VCC, VBIAS1 to 3, 1.8 V or less)

A circuit to turn OFF the output when detecting V_{CC} and VBIAS1 to 3 during low voltage is not inserted. Turn OFF the output in STBY below the operation range.

CT1 and CT2

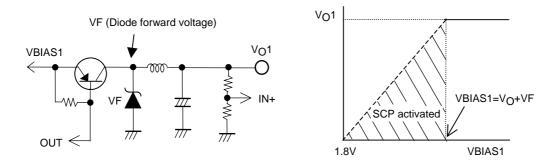
CT1 and CT2 have the waveform mutually displaced by 180 degrees in the phase. Independent frequency setting is impossible. Set the same value for capacitors to be connected, CT1 and CT2.

Relationship between short-circuit protection and soft start

The soft start condition is judged to be a short-circuit condition and charge to C_{SCP} is continued. Set the soft start time tSOFT shorter than the set time tSOFT for short-circuit protection.

Use in the step-down circuit (ch1)

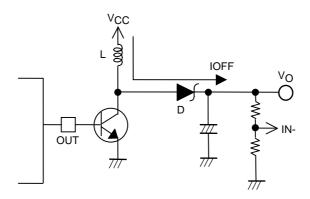
The step-down application as shown below is judged to be the short-circuit condition with VBIAS1 lower than the set voltage of $V_{O}+VF$ and SCP is activated.



With VBIAS1<VO+VF at step-down

Use of the step-up circuit (Ch2, Ch3)

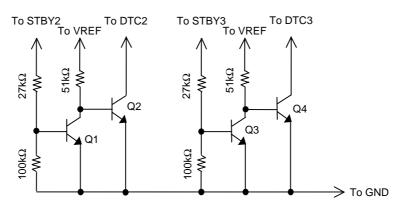
As shown in the figure, the step-up application forms a through via a $V_{CC} \rightarrow L \rightarrow D$ route in the STBY OFF mode, so that the voltage remains in V_O. Similarly, the voltage remains in V_O in the SCP run mode. If necessary, cut off the through route with a switch.



When a chopper step-up circuit is used

Soft start of Ch2 and Ch3

Ch2 and Ch3 cannot perform soft start when VREF is started in advance because a DTC discharge circuit is not provided. Provide this discharge circuit.

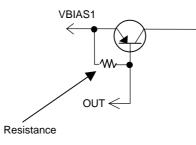


Set Q1 and Q3 to the threshold value of 0.89 V while assuming VBE = 0.7V.

Plan with an external DTC pin discharge circuit

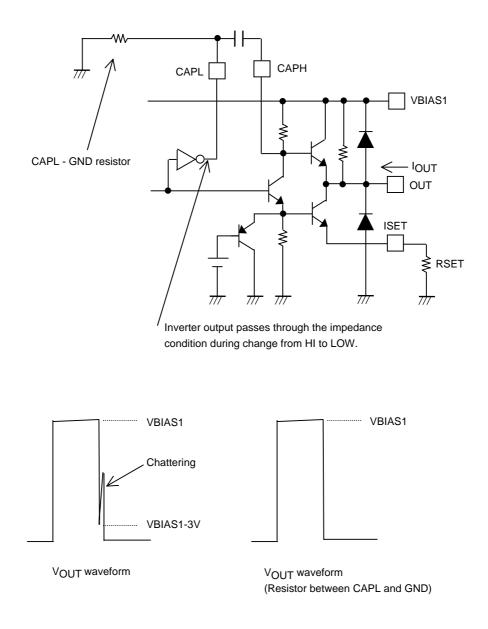
Resistance between the base and emitter of external PNP transistor (or between the gate and source in the case of MOS transistor)

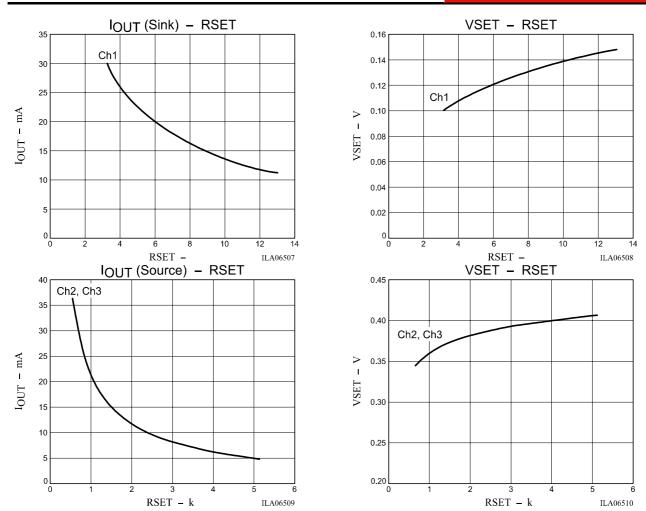
During light-load operation, the switching speed of transistor on the sink side of output stage is delayed, so that the external transistor cannot be turned OFF completely, resulting in increase in the current drain. Insert resistance between the base and emitter of external PNP transistor (or between the gate and source of MOS transistor) to ensure switching-off under light load and to prevent increase in the current drain.



Resistance between CAPL and GND during MOS drive

V_{OUT} develops chattering with VBIAS1 at about -3V. This is considered due to the high impedance condition sensitive to noise in the course of change of the inverter output shown below from HI to LOW. Provide a resistor to CAPL - GND to improve the high impedance condition to eliminate chattering.





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